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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/518,880	08/08/2005	Hans-Joachim Barth	10808/158	5306
48581	7590	02/06/2008	EXAMINER	
BRINKS HOFER GILSON & LIONE INFINEON PO BOX 10395 CHICAGO, IL 60610			GOODWIN, DAVID J	
		ART UNIT	PAPER NUMBER	
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**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>
	10/518,880	BARTH ET AL.
	<b>Examiner</b>	<b>Art Unit</b>
	DAVID GOODWIN	2818

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) Responsive to communication(s) filed on 31 December 2007.  
 2a) This action is FINAL.      2b) This action is non-final.  
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) Claim(s) 25-32 and 34-50 is/are pending in the application.  
 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.  
 5) Claim(s) \_\_\_\_\_ is/are allowed.  
 6) Claim(s) 25-32 and 34-50 is/are rejected.  
 7) Claim(s) \_\_\_\_\_ is/are objected to.  
 8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) The specification is objected to by the Examiner.  
 10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.  
     Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
     Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).  
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
 a) All    b) Some \* c) None of:  
 1. Certified copies of the priority documents have been received.  
 2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)          | 4) <input type="checkbox"/> Interview Summary (PTO-413)           |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ .                                    |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)          | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date _____ .  | 6) <input type="checkbox"/> Other: _____ .                        |

## DETAILED ACTION

### ***Claim Rejections - 35 USC § 112***

1. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

2. Claim <sup>42</sup> <sub>1</sub> is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
3. Claim <sup>42</sup> <sub>1</sub> recites " a structure" in line 4 and "a useful structure" in line 9.
4. It is unclear if these are one and the same structure.

### ***Claim Rejections - 35 USC § 102***

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 25-28, 30, 31, 32, 34 –37, 39, 41-44, 47, 49, and 50 are rejected under 35 U.S.C. 102(e) as being anticipated by Hsu (US 6,555,467).
3. Regarding claim 25.
4. Hsu teaches a semiconductor arrangement. Said arrangement comprises a substrate (12) (fig 1) (column 2 lines 20-30). A layer arranged on the substrate (12).

The layer including a first subregion (18) and a second subregion (42, 72) arranged proximate the first subregion (18) (fig 7). The first subregion (18) being a decomposable material (column 2 lines 30-60) and the second subregion (42) having a structure of non-decomposable material (column 3 lines 10-40). A covering layer (82) positioned on the layer, including the first and second subregion (column 4 lines 55-65). An electrically conductive passivation layer (40, 70) positioned between adjacent surface of the non-decomposable material and the covering layer (82) (fig 11) (column 4 lines 50-65). Wherein the decomposable material (18) is diffusible through the covering layer (82) (fig 11,12) (column 5 lines 1-5). And the covering layer mechanically closes the first subregion off to the outside world.

5. Regarding claim 26.
6. Hsu teaches an intermediate layer (16) between the substrate (12) and the layer of decomposable material (18) (fig 7) (column 2 lines 30-40).
7. Regarding claim 27.
8. Hsu teaches that the covering material (82) comprises a dielectric material (fig 11) (column 4 lines 55-65).
9. Regarding claim 28.
10. Hsu teaches that the covering layer comprises silicon oxide (column 4 lines 55-65).
11. Regarding claim 30.
12. Hsu teaches that the decomposable material (18) is diffusible through the covering layer (82) (fig 11,12) (column 5 lines 1-5).

13. Regarding claim 31.

14. Hsu teaches that the structure of the non-decomposable material (42, 72) is an electrically conductive material (column 3 lines 25-45).

15. Regarding claim 32

16. Hsu teaches that the structure of the non-decomposable material (42, 72) is copper (column 3 lines 25-45).

17. Regarding claim 34.

18. The nondecomposable structure comprises a dielectric material (80) (column 4 lines 50-60).

19. Regarding claim 35.

20. The nondecomposable structure comprises a silicon nitride (80) (column 4 lines 50-60).

21. Regarding claim 36.

22. Hsu teaches that the decomposable material (18) is thermally decomposable . (column 5 lines 1-5).

23. Regarding claim 37.

24. Hsu teaches that the thermally decomposable material (18) is polynorbornene (column 2 line 30-50).

25. Regarding claim 39.

26. At least one supporting structure (42, 72) is formed in the layer arranged between the substrate (12) and covering layer (82) (fig 11).

27. Regarding claim 41.

28. A protective passivation layer (40) at least partially surrounds the structure (fig 10).
29. Regarding claim 42.
30. Hsu teaches a method of making a semiconductor arrangement. Said method comprises a substrate (12) (fig 1) (column 2 lines 20-30). Forming a layer arranged on the substrate (12). The layer including a first subregion (18) and a second subregion (42, 72) arranged proximate the first subregion (18) (fig 7). The first subregion (18) being a decomposable material (column 2 lines 30-60) and the second subregion (42) having a structure of non-decomposable material (column 3 lines 10-40). Forming a covering layer (46, 82) positioned on the layer (column 4 lines 55-65). Forming an electrically conductive passivation layer (40, 70) positioned between adjacent surfaces of the structure of the non-decomposable material and the covering layer (82) (fig 11) (column 4 lines 50-65). Wherein the decomposable material (18) is diffusible through the covering layer (82) the first subregion is mechanically closed off to the outside world (fig 11,12) (column 5 lines 1-5).
31. Regarding claim 43.
32. Hsu teaches the decomposable material is encased in a casing comprising the substrate (12), the non-decomposable material (42, 72) and the covering material (82) (fig 10).
33. Regarding claim 44.
34. Hsu teaches that the decomposable material (18) is thermally decomposable (column 5 lines 1-5).

35. Regarding claim 47.

36. Hsu teaches depositing and patterning the decomposable material (18) on the substrate (12) (fig 6) (column 3 lines 10-30). Depositing (the material of the structure (42, 72) on the substrate (fig 7). Planarizing the surface of the deposited decomposable material and material of the structure (42) (fig 7) (column 3 lines 30-40).

37. Regarding claim 49.

38. Hsu teaches that at least one additional layer stack is formed on the covering layer (fig 11). The additional layer stack having an additional covering layer on an additional layer comprising decomposable material and a useful structure (fig 11, 12).

39. Regarding claim 50.

40. Hsu teaches that the structures that are separated by a covering layer (46) are coupled by at least one contact hole being introduced into the covering layer and being filled with electrically conductive material (fig 11).

#### ***Claim Rejections - 35 USC § 103***

41. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

42. Claims 40 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (US 6,555,467) as applied to claim 24 and further in view of Ibanbdeljalil (US 6,365,958).

43. Regarding claim 40.

Art Unit: 2818

44. Hsu teaches elements of the claimed invention above.
45. Hsu does not teach forming a protective structure along a lateral boundary of the substrate.
46. Ibanabdeljalil teaches forming protective structure (105) along a lateral boundary of a device having interconnect (104) thereon (fig 7a-7b) (column 11 lines 20-65).
47. It would have been obvious to put a protective structure taught by Ibanabdeljalil along the boundary of the substrate taught by Hsu in order to reduce the susceptibility to stress cracking of the device.
48. Claim 29 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (US 6,555,467) as applied to claim 24 and further in view of Brown (US 6,030,896).
49. Regarding claim 29.
50. Hsu teaches elements of the claimed invention above.
51. Hsu does not teach forming the structure on a silicon substrate.
52. Brown teaches forming an interconnect structure on a silicon substrate (column 4 lines 10-30).
53. It would have been obvious to one of ordinary skill in the art to form the structure on a silicon substrate so that active devices can be formed in the substrate and be connected to the interconnect.
54. Claim 46 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (US 6,555,467) as applied to claim 42 and further in view of Ito (US 6,573,607).
55. Regarding claim 46
56. Hsu teaches elements of the claimed invention above.

Art Unit: 2818

57. Hsu does not teach forming the barrier layer by CVD.

58. Ito teaches forming a metal barrier layer for copper interconnect by CVD deposition of tantalum (column 4 lines 10-25).

59. It would have been obvious to one of ordinary skill in the art to form a barrier layer for a copper interconnect structure by CVD in order to form a highly conformal layer which will prevent copper out diffusion.

60. Claim 48 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (US 6,555,467) as applied to claim 42 and further in view of Brown (US 6,030,896).

61. Regarding claim 48.

62. Hsu teaches elements of the claimed invention above.

63. Hsu does not teach depositing and patterning the structure material and then planarizing the surface.

64. Brown teaches a method of making a device. Said method comprises depositing a conductive material (18) (fig 1) and then patterning said material (fig 2) (column 4 lines 20-50). A dielectric (24) is then formed between the lines of conductive material and planarized (fig 4) (column 5 lines 5-20).

65. It would have been obvious to one of ordinary skill in the art to pattern the metal layer prior to the deposition of the dielectric in order to reduce the chance of copper contamination and to prevent reduce to the underlying patterns.

66. Claim 38 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (US 6,555,467) as applied to claim 24 and further in view of Kohl (US 2002/0081787).

67. Regarding claim 38.

68. Hsu teaches elements of the claimed invention above.
69. Hsu does not teach that the decomposable material may be photosensitive.
70. Kohl teaches the use of a photosensitive decomposable material in the formation interconnect dielectric (paragraph 0080).
71. It would have been obvious to one of ordinary skill in the art to make the decomposable material photosensitive in so that less thermal energy is required to decompose the material.
72. Claim 45 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (US 6,555,467) as applied to claim 42 and further in view of Leu (US 6,605,874).
73. Regarding claim 45.
74. Hsu teaches elements of the claimed invention above.
75. Hsu teaches that the structure of the non-decomposable material (42, 72) is copper (column 3 lines 25-45).
76. Hsu does not teach that a barrier layer comprises cobalt phosphorous.
77. Leu teaches forming a barrier layer (118) on interconnect by electroless deposition (column 13 lines 10-18)
78. It would have been obvious to one of ordinary skill in the art to form a cobalt phosphorous barrier layer in order to prevent copper diffusion.
- 79.

***Response to Arguments***

80. Applicant's arguments filed 12/31/2007 have been fully considered but they are not persuasive.

81. The applicant argues that Hsu does not teach a covering layer position on the non-decomposable layer. The applicant further argues that claim 25 makes clear that the passivation layer is on top of the non-decomposable material.

82. The applicant is incorrect. The claim does not limit the location of the passivation layer to on top of the non-decomposable material, Therefore passivation located on the side of the non-decomposable material satisfies the claim. As the applicant notes, page 11 line 14 of the remarks, *on* can refer to material located adjacent the side of the non-decomposable material “on the side.”

### ***Conclusion***

83. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DAVID GOODWIN whose telephone number is (571)272-8451. The examiner can normally be reached on Monday through Friday, 9:00am through 5:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Steven Loke can be reached on (571)272-1657. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

DJG

STEVEN LOKE  
SUPERVISORY PATENT EXAMINER

